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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC564/HD74HC574

Octal D-type Flip-Flops (with 3-state outputs)



ADE-205-510 (Z)
1st. Edition
Sep. 2000

Description



These devices are positive edge triggered flip-flops. The difference between HD74HC564 and HD74HC574 is only that the former has inverting outputs and the latter has noninverting outputs.

Data at the D inputs, meeting the set-up and hold time requirements, are transferred to the Q or \bar{Q} outputs on positive going transitions of the clock (CK) input. When a high logic level is applied to the output control (OC) input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

Features

- High Speed Operation: t_{pd} (Clock to Output) = 13 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

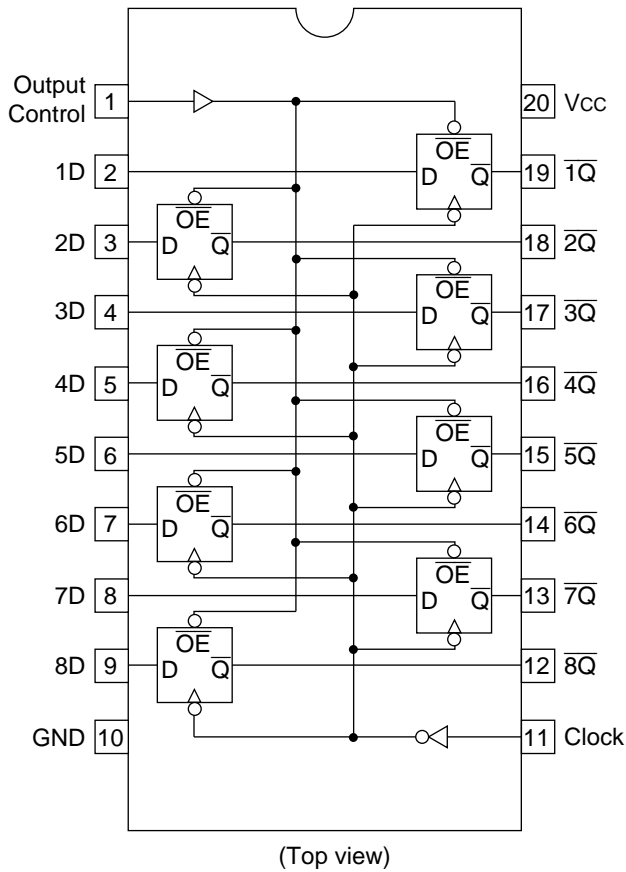
Output Control	Clock	Data	Outputs	
			HD74HC564	HD74HC574
L		H	L	H
L		L	H	L
L	L	X	\bar{Q}_0	Q_0
H	X	X	Z	Z

Q_0 : level of Q before the indicated Steady-state input conditions were established.

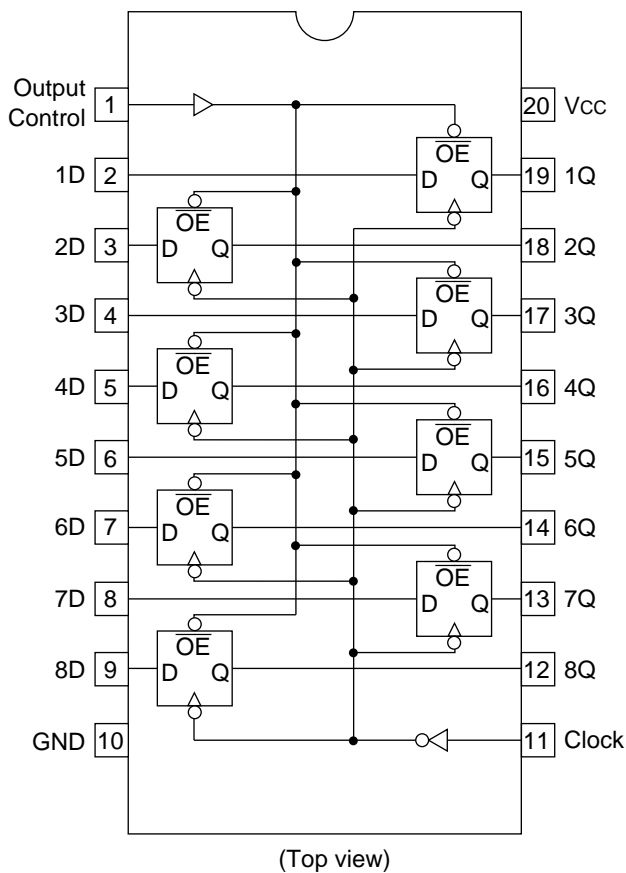
\bar{Q}_0 : complement of Q_0 or level of \bar{Q} before the indicated Steady-state input Conditions were established.

Pin Arrangement

HD74HC564



HD74HC574



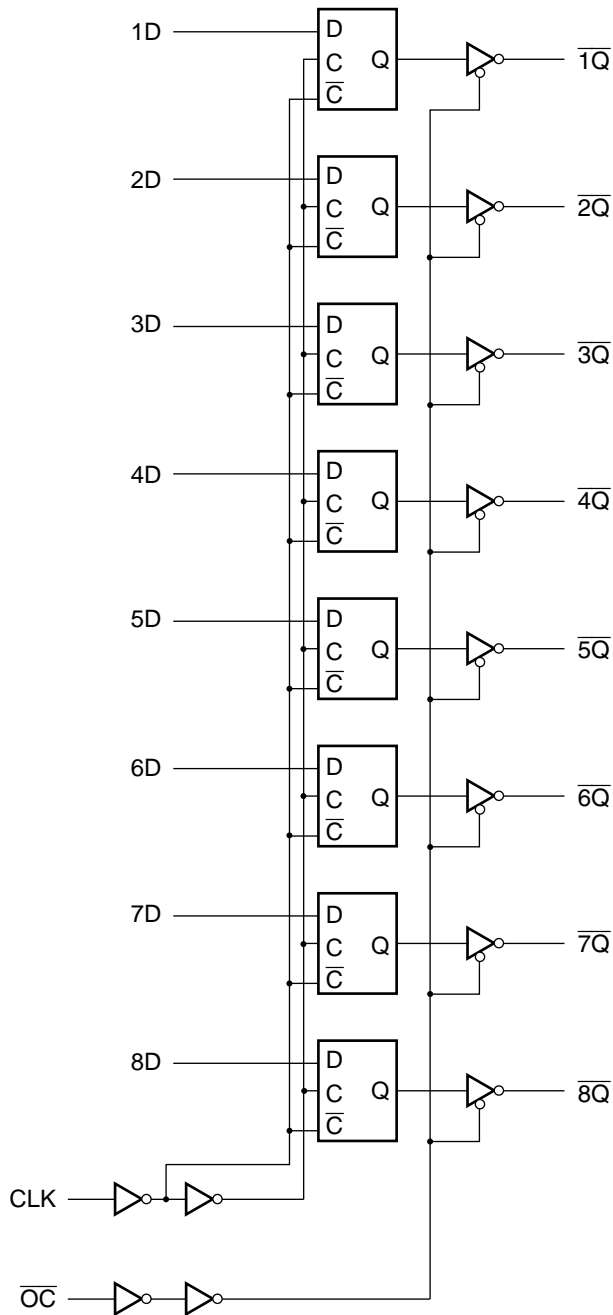
Absolute Maximum Ratings

Item	Symbol	Rating	Unit
Supply voltage range	V_{CC}	-0.5 to +7.0	V
Input voltage	V_{IN}	-0.5 to $V_{CC} + 0.5$	V
Output voltage	V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Output current	I_{OUT}	± 35	mA
DC current drain per V_{CC} , GND	I_{CC} , I_{GND}	± 75	mA
DC input diode current	I_{IK}	± 20	mA
DC output diode current	I_{OK}	± 20	mA
Power Dissipation per package	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	$^{\circ}C$

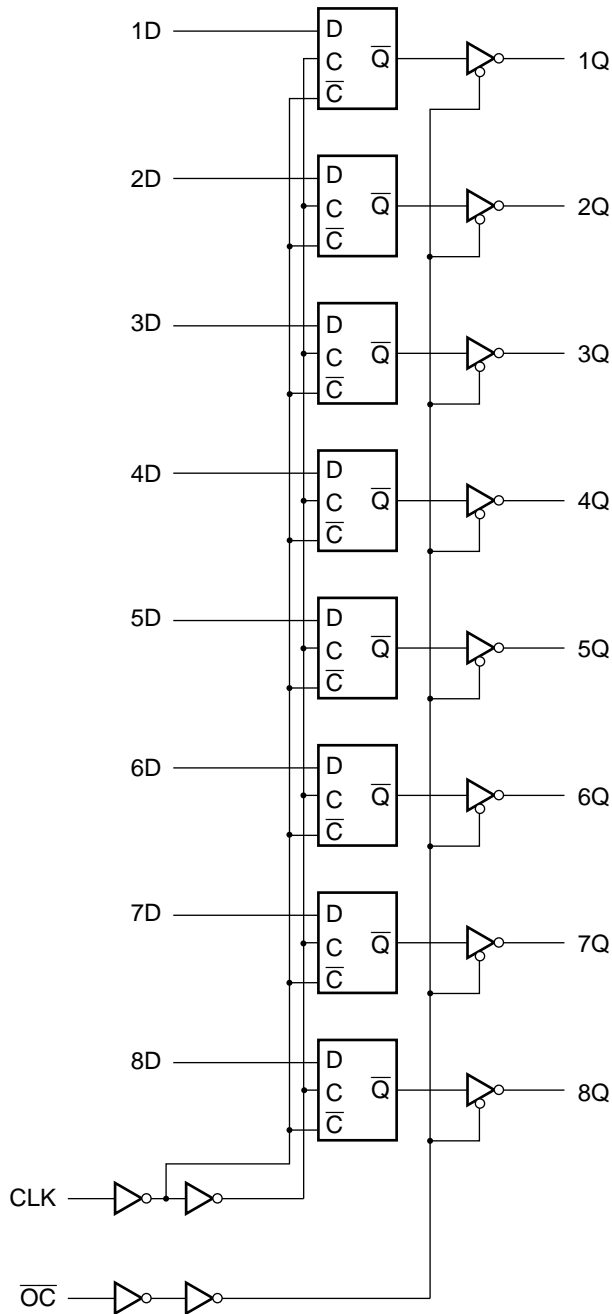
HD74HC564/HD74HC574

Block Diagram

HD74HC564



HD74HC574



DC Characteristics

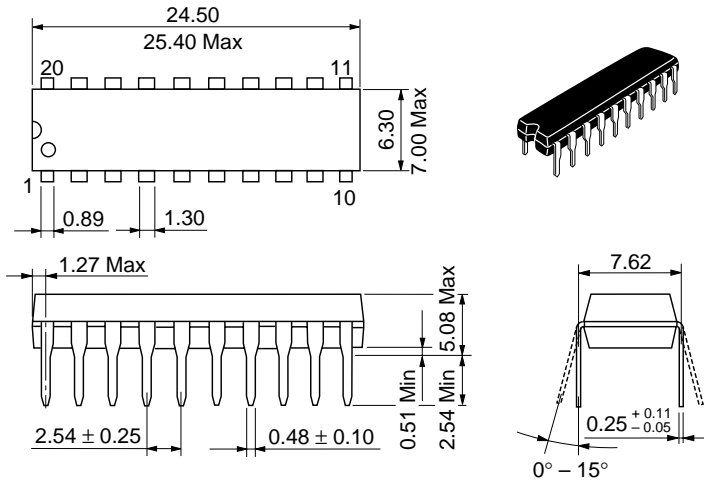
Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -6 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -7.8 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 6 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 7.8 mA
Off-state output current	I _{OZ}	6.0	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND	
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA	

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Maximum clock frequency	f_{max}	2.0	—	—	6	—	5	MHz	
		4.5	—	—	30	—	24		
		6.0	—	—	35	—	28		
Propagation delay time	t_{PLH} t_{PHL}	2.0	—	—	155	—	195	ns	Clock to output
		4.5	—	13	31	—	39		
		6.0	—	—	26	—	33		
Output enable time	t_{ZH} t_{ZL}	2.0	—	—	150	—	190	ns	
		4.5	—	13	30	—	38		
		6.0	—	—	26	—	33		
Output disable time	t_{HZ} t_{LZ}	2.0	—	—	150	—	190	ns	
		4.5	—	15	30	—	38		
		6.0	—	—	26	—	33		
Setup time	t_{su}	2.0	—	—	100	—	125	ns	
		4.5	—	1	20	—	25		
		6.0	—	—	17	—	21		
Hold time	t_h	2.0	5	—	—	5	—	ns	
		4.5	5	0	—	5	—		
		6.0	5	—	—	5	—		
Pulse width	t_w	2.0	80	—	—	100	—	ns	
		4.5	16	4	—	20	—		
		6.0	14	—	—	17	—		
Output rise/fall time	t_{TLH} t_{THL}	2.0	—	—	60	—	75	ns	
		4.5	—	4	12	—	15		
		6.0	—	—	10	—	13		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

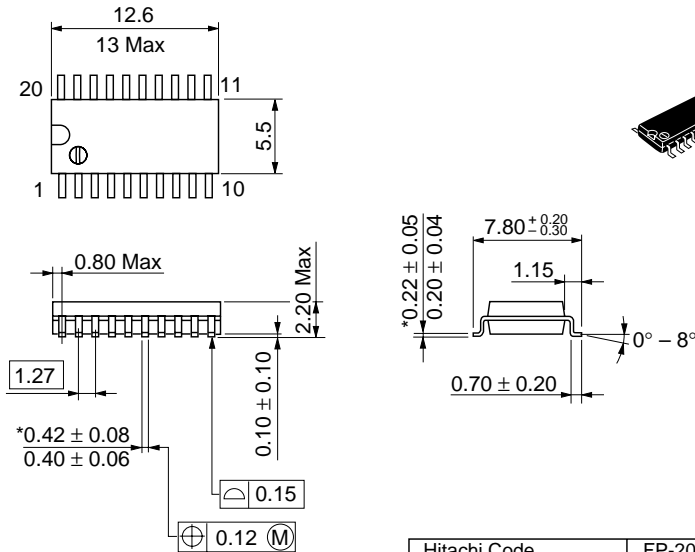
Package Dimensions

Unit: mm



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Mass (reference value)	1.26 g

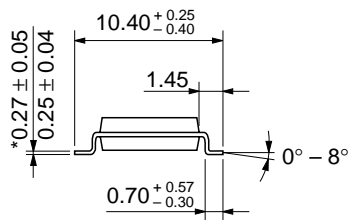
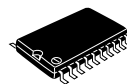
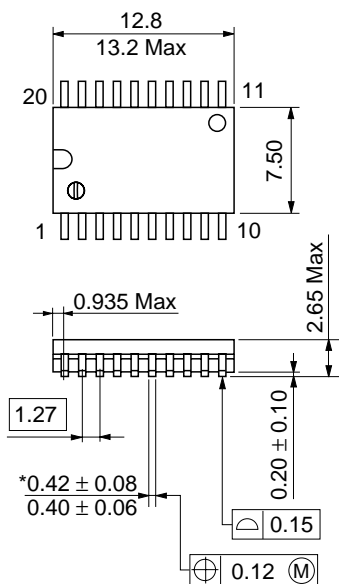
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.31 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.52 g

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